LM2990 Negative Low Dropout Regulator

Check for Samples: LM2990

FEATURES

- **5% Output Accuracy over Entire Operating Range**
- **Output Current in Excess of 1A**
- **Dropout Voltage Typically 0.6V at 1A Load**
- **Low Quiescent Current**
- **Internal Short Circuit Current Limit**
- **Internal Thermal Shutdown with Hysteresis**
- **Functional Complement to the LM2940 Series**

APPLICATIONS

- **Post Switcher Regulator**
- **Local, On-Card, Regulation**
- **Battery Operated Equipment**

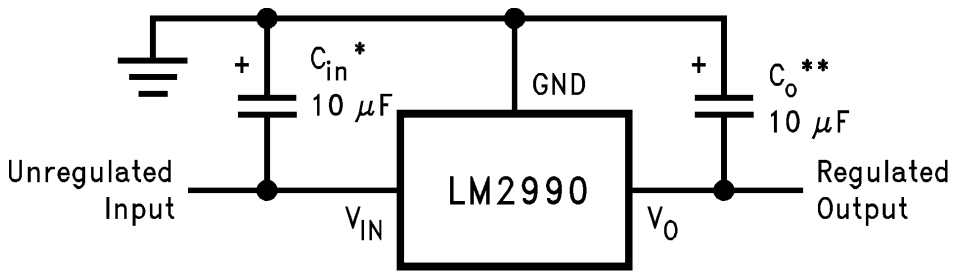
DESCRIPTION

The LM2990 is a three-terminal, low dropout, 1 ampere negative voltage regulator available with fixed output voltages of −5, −5.2, −12, and −15V.

The LM2990 uses new circuit design techniques to provide low dropout and low quiescent current. The dropout voltage at 1A load current is typically 0.6V and an ensured worst-case maximum of 1V over the entire operating temperature range. The quiescent current is typically 1 mA with 1A load current and an input-output voltage differential greater than 3V. A unique circuit design of the internal bias supply limits the quiescent current to only 9 mA (typical) when the regulator is in the dropout mode ($V_{OUT} - V_{IN} \leq 3V$). Output voltage accuracy is ensured to ±5% over load, and temperature extremes.

The LM2990 is short-circuit proof, and thermal shutdown includes hysteresis to enhance the reliability of the device when overloaded for an extended period of time. The LM2990 is available in a 3-lead package and is rated for operation over the automotive temperature range of −40°C to +125°C.

Typical Application



*Required if the regulator is located further than 6 inches from the power supply filter capacitors. A 1 μF solid tantalum or a 10 μF aluminum electrolytic capacitor is recommended.
**Required for stability. Must be at least a 10 μF aluminum electrolytic or a 1 μF solid tantalum to maintain stability. May be increased without bound to maintain regulation during transients. Locate the capacitor as close as possible to the regulator. The equivalent series resistance (ESR) is critical, and should be less than 10Ω over the same operating temperature range as the regulator.

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Connection Diagrams

Front View

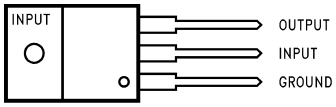

Figure 1. 3-Lead TO-220 Package
See Package Number NDE0003B

Top View

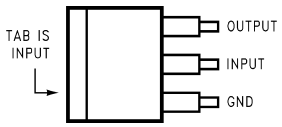

Figure 2. Surface-Mount DDPAK/TO-263 Package
See Package Number KTT0003B

Side View

Figure 3. Surface-Mount DDPAK/TO-263 Package
See Package Number KTT0003B

Top View

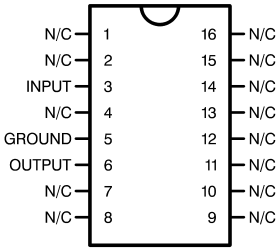

Figure 4. 16-Lead CDIP Package
See Package Number NFE0016A

Top View

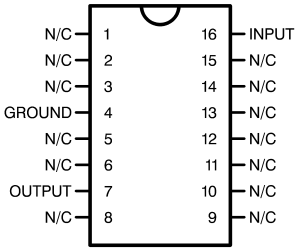

Figure 5. 16-Lead CLGA Package
See Package Number NAC0016A

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings[(1)(2)]

Input Voltage		−26V to +0.3V
ESD Susceptibility[(3)]		2 kV
Power Dissipation[(4)]		Internally Limited
Junction Temperature (T_{Jmax})		125°C
Storage Temperature		−65°C to +150°C
Soldering Temperature	TO-220 (T), Wave	260°C, 10 sec
	DDPAK/TO-263 (S)	235°C, 30 sec

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
(3) Human body model, 100 pF discharged through a 1.5 kΩ resistor.
(4) The maximum power dissipation is a function of T_{Jmax}, θ_{JA}, and T_A. The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{Jmax} - T_A)/\theta_{JA}$. If this dissipation is exceeded, the die temperature will rise above 125°C, and the LM2990 will eventually go into thermal shutdown at a T_J of approximately 160°C. For the LM2990, the junction-to-ambient thermal resistance, is 53°C/W, 73°C/W for the DDPAK/TO-263, and the junction-to-case thermal resistance is 3°C. If the DD[AK/TO-263 package is used, the thermal resistance can be reduced by increasing the P.C. board copper area thermally connected to the package. Using 0.5 square inches of copper area, θ_{JA} is 50°C/W; with 1 square inch of copper area, θ_{JA} is 37°C/W; and with 1.6 or more square inches of copper area, θ_{JA} is 32°C/W.

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Operating Ratings[1]

Junction Temperature Range (T_J)	−40°C to +125°C
Maximum Input Voltage (Operational)	−26V

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics.

Electrical Characteristics

V_{IN} = −5V + $V_{O(NOM)}$[1], I_O = 1A, C_O = 47 µF, unless otherwise specified. **Boldface** limits apply over the entire operating temperature range, −40°C ≤ T_J ≤ 125°C, all other limits apply for T_J = 25°C.

Parameter	Conditions	LM2990-5.0		LM2990-5.2		Units (Limit)
		Typ[2]	Limit[3]	Typ[2]	Limit[3]	
Output Voltage (V_O)	5 mA ≤ I_O ≤ 1A	−5	−4.90	−5.2	−5.10	V (max)
			−5.10		−5.30	mV (min)
						V
	5 mA ≤ I_O ≤ 1A		**−4.75**		**−4.94**	V (max)
			−5.25		**−5.46**	V (min)
Line Regulation	I_O = 5 mA, $V_{O(NOM)}$ −1V > V_{IN} > −26V	4	40	4	40	mV (max)
Load Regulation	50 mA ≤ I_O ≤ 1A	1	40	1	40	mV (max)
Dropout Voltage	I_O = 0.1A, ΔV_O ≤ 100 mV	0.1	**0.3**	0.1	**0.3**	V (max)
	I_O = 1A, ΔV_O ≤ 100 mV	0.6	**1**	0.6	**1**	V (max)
Quiescent Current (I_q)	I_O ≤ 1A	1	5	1	5	mA (max)
	I_O = 1A, V_{IN} = $V_{O(NOM)}$	9	50	9	50	mA (max)
Short Circuit Current	R_L = 1Ω[4]	1.8	1.5	1.8	1.5	A (min)
Maximum Output Current	See[4]	1.8	1.5	1.8	1.5	A (min)
Ripple Rejection	V_{ripple} = 1 V_{rms}, f_{ripple} = 1 kHz, I_O = 5 mA	58	50	58	50	dB (min)
Output Noise Voltage	10 Hz–100 kHz, I_O = 5 mA	250	750	250	750	µV (max)
Long Term Stability	1000 Hours	2000		2000		ppm

(1) $V_{O(NOM)}$ is the nominal (typical) regulator output voltage, −5V, −5.2V, −12V or −15V.
(2) Typicals are at T_J = 25°C and represent the most likely parametric norm.
(3) Limits are specified and 100% production tested.
(4) The short circuit current is less than the maximum output current with the −12V and −15V versions due to internal foldback current limiting. The −5V and −5.2V versions, tested with a lower input voltage, does not reach the foldback current limit and therefore conducts a higher short circuit current level. If the LM2990 output is pulled above ground, the maximum allowed current sunk back into the LM2990 is 1.5A.

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Electrical Characteristics

V_{IN} = −5V + $V_{O(NOM)}$ (1), I_O = 1A, C_O = 47 µF, unless otherwise specified. **Boldface** limits apply over the entire operating temperature range, −40°C ≤ T_J ≤ 125°C, all other limits apply for T_J = 25°C.

Parameter	Conditions	LM2990-12		LM2990-15		Units (Limit)
		Typ (2)	Limit (3)	Typ (2)	Limit (3)	
Output Voltage (V_O)	5 mA ≤ I_O ≤ 1A	−12	−11.76	−15	−14.70	V (max)
			−12.24		−15.30	V (min)
	5 mA ≤ I_O ≤ 1A					V
			−11.40		**−14.25**	V (max)
			−12.60		**−15.75**	V (min)
Line Regulation	I_O = 5 mA, $V_{O(NOM)}$ −1V > V_{IN} > −26V	6	60	6	60	mV (max)
Load Regulation	50 mA ≤ I_O ≤ 1A	3	50	3	50	mV (max)
Dropout Voltage	I_O = 0.1A, ΔV_O ≤ 100 mV	0.1	**0.3**	0.1	**0.3**	V (max)
	I_O = 1A, ΔV_O ≤ 100 mV	0.6	**1**	0.6	**1**	V (max)
Quiescent Current (I_q)	I_O ≤ 1A	1	5	1	5	mA (max)
	I_O = 1A, V_{IN} = $V_{O(NOM)}$	9	50	9	50	mA (max)
Short Circuit Current	R_L = 1Ω (4)	1.2	0.9	1.0	0.75	A (min)
Maximum Output Current	See (4)	1.8	1.4	1.8	1.4	A (min)
Ripple Rejection	V_{ripple} = 1 V_{rms}, f_{ripple} = 1 kHz, I_O = 5 mA	52	42	52	42	dB (min)
Output Noise Voltage	10 Hz–100 kHz, I_O = 5 mA	500	1500	600	1800	µV (max)
Long Term Stability	1000 Hours	2000		2000		ppm

(1) $V_{O(NOM)}$ is the nominal (typical) regulator output voltage, −5V, −5.2V, −12V or −15V.
(2) Typicals are at T_J = 25°C and represent the most likely parametric norm.
(3) Limits are specified and 100% production tested.
(4) The short circuit current is less than the maximum output current with the −12V and −15V versions due to internal foldback current limiting. The −5V and −5.2V versions, tested with a lower input voltage, does not reach the foldback current limit and therefore conducts a higher short circuit current level. If the LM2990 output is pulled above ground, the maximum allowed current sunk back into the LM2990 is 1.5A.

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Definition of Terms

Dropout Voltage: The input-output voltage differential at which the circuit ceases to regulate against further reduction in input voltage. Measured when the output voltage has dropped 100 mV from the nominal value obtained at (V_O + 5V) input, dropout voltage is dependent upon load current and junction temperature.

Input Voltage: The DC voltage applied to the input terminals with respect to ground.

Input-Output Differential: The voltage difference between the unregulated input voltage and the regulated output voltage for which the regulator will operate.

Line Regulation: The change in output voltage for a change in the input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that the average chip temperature is not significantly affected.

Load Regulation: The change in output voltage for a change in load current at constant chip temperature.

Long Term Stability: Output voltage stability under accellerated life-test conditions after 1000 hours with maximum rated voltage and junction temperature.

Output Noise Voltage: The rms AC voltage at the output, with constant load and no input ripple, measured over a specified frequency range.

Quiescent Current: That part of the positive input current that does not contribute to the positive load current. The regulator ground lead current.

Ripple Rejection: The ratio of the peak-to-peak input ripple voltage to the peak-to-peak output ripple voltage.

Temperature Stability of V_O: The percentage change in output voltage for a thermal variation from room temperature to either temperature extreme.

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Typical Performance Characteristics

Dropout Voltage

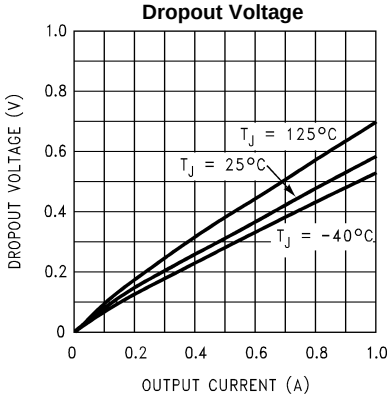

Figure 6.

Normalized Output Voltage

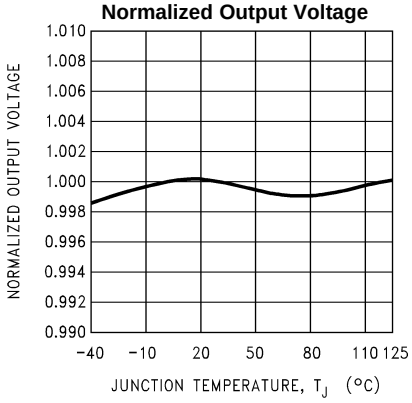

Figure 7.

LM2990-5.0 and LM2990-5.2 Quiescent Current

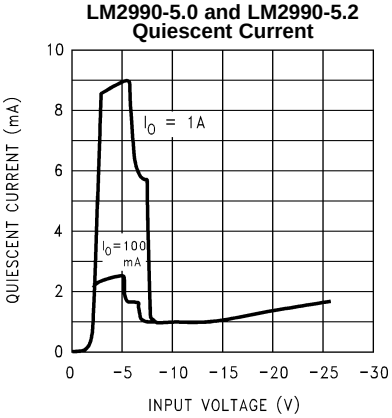

Figure 8.

LM2990-12 Quiescent Current

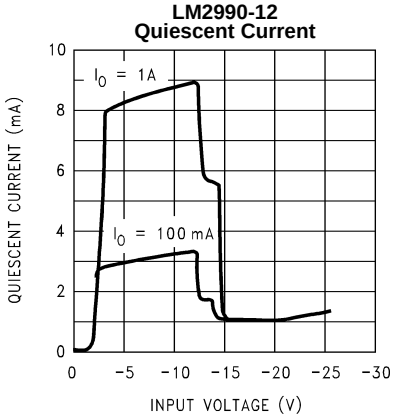

Figure 9.

LM2990-15 Quiescent Current

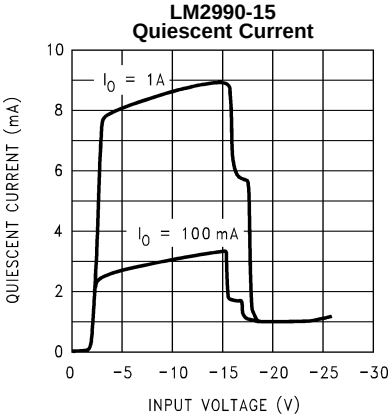

Figure 10.

LM2990-5 and LM2990-5.2 Low Voltage Behavior

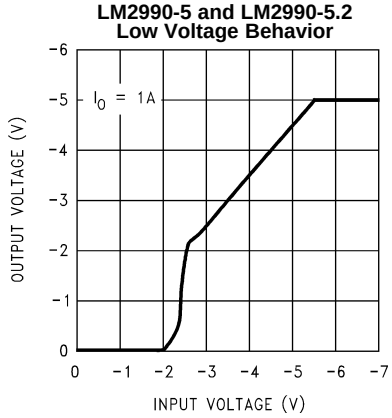

Figure 11.

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Typical Performance Characteristics (continued)

LM2990-5 and LM2990-5.2 Line Transient Response

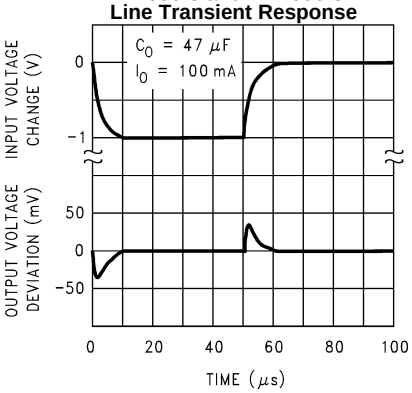

Figure 12.

LM2990-5 and LM2990-5.2 Load Transient Response

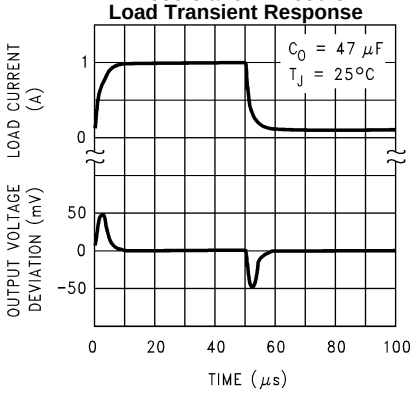

Figure 13.

LM2990-12 and LM2990-15 Low Voltage Behavior

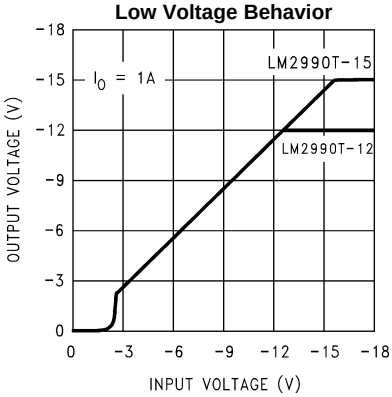

Figure 14.

LM2990-12 and LM2990-15 Line Transient Response

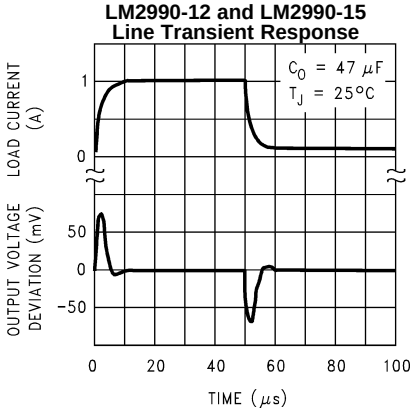

Figure 15.

LM2990-12 and LM2990-15 Load Transient Response

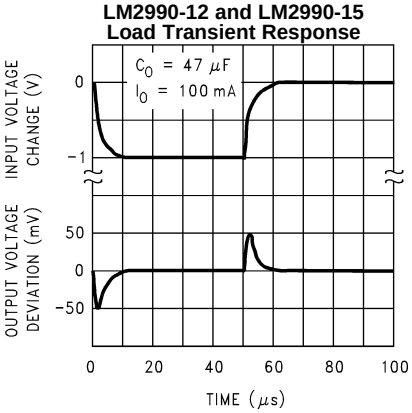

Figure 16.

LM2990-5 and LM2990-5.2 Ripple Rejection

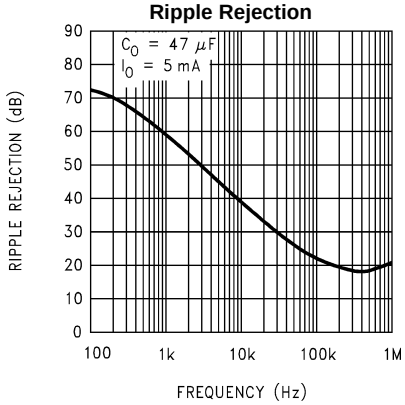

Figure 17.

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Typical Performance Characteristics (continued)

LM2990-5 and LM2990-5.2 Output Impedance

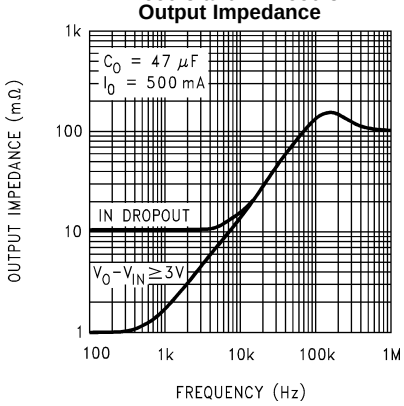

Figure 18.

Maximum Output Current

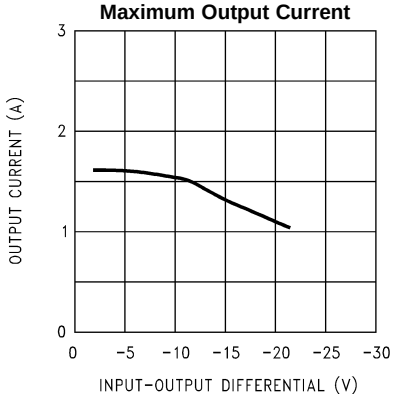

Figure 19.

LM2990-12 and LM2990-15 Ripple Rejection

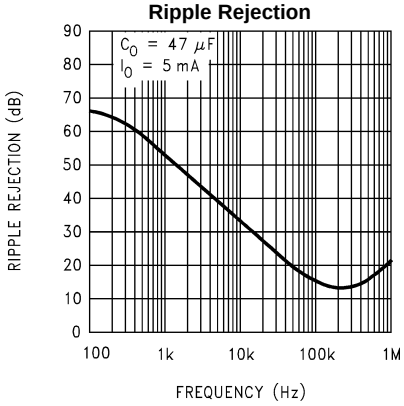

Figure 20.

LM2990-12 and LM2990-15 Output Impedance

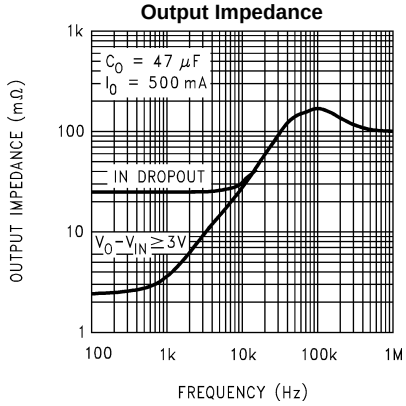

Figure 21.

Maximum Output Current

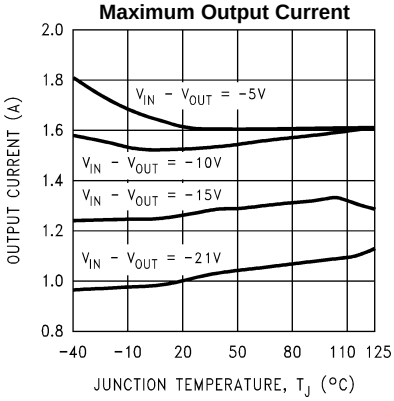

Figure 22.

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Typical Performance Characteristics (continued)

Maximum Power Dissipation (TO-220)

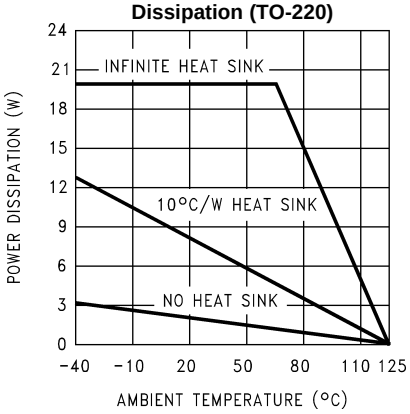

Figure 23.

Maximum Power Dissipation (TO-263)(1)

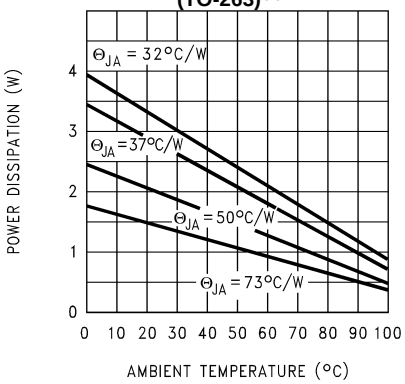

Figure 24.

(1) The maximum power dissipation is a function of T_{Jmax}, θ_{JA}, and T_A. The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{Jmax} - T_A)/\theta_{JA}$. If this dissipation is exceeded, the die temperature will rise above 125°C, and the LM2990 will eventually go into thermal shutdown at a T_J of approximately 160°C. For the LM2990, the junction-to-ambient thermal resistance, is 53°C/W, 73°C/W for the DDPAK/TO-263, and the junction-to-case thermal resistance is 3°C. If the DD[AK/TO-263 package is used, the thermal resistance can be reduced by increasing the P.C. board copper area thermally connected to the package. Using 0.5 square inches of copper area, θ_{JA} is 50°C/W; with 1 square inch of copper area, θ_{JA} is 37°C/W; and with 1.6 or more square inches of copper area, θ_{JA} is 32°C/W.

Typical Applications

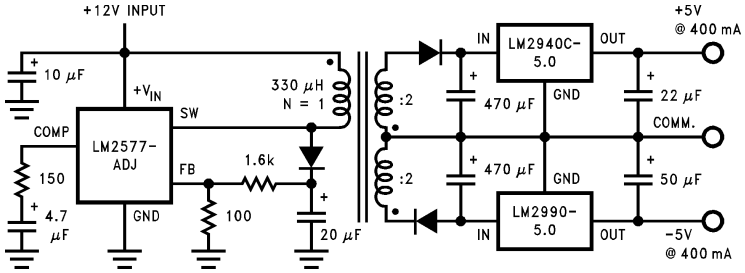

Figure 25. Post Regulator for an Isolated Switching Power Supply

The LM2940 is a positive 1A low dropout regulator; refer to its datasheet for further information.

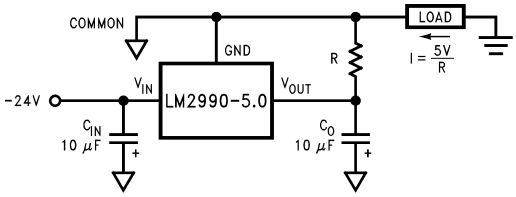

Figure 26. Fixed Current Sink

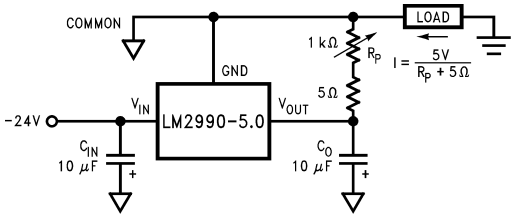

Figure 27. Adjustable Current Sink

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APPLICATION HINTS

EXTERNAL CAPACITORS

The LM2990 regulator requires an output capacitor to maintain stability. The capacitor must be at least 10 μF aluminum electrolytic or 1 μF solid tantalum. The output capacitor's ESR must be less than 10Ω, or the zero added to the regulator frequency response by the ESR could reduce the phase margin, creating oscillations (refer to the graph on the right). An input capacitor, of at least 1 μF solid tantalum or 10 μF aluminum electrolytic, is also needed if the regulator is situated more than 6″ from the input power supply filter.

FORCING THE OUTPUT POSITIVE

Due to an internal clamp circuit, the LM2990 can withstand positive voltages on its output. If the voltage source pulling the output positive is DC, the current must be limited to 1.5A. A current over 1.5A fed back into the LM2990 could damage the device. The LM2990 output can also withstand fast positive voltage transients up to 26V, without any current limiting of the source. However, if the transients have a duration of over 1 ms, the output should be clamped with a Schottky diode to ground.

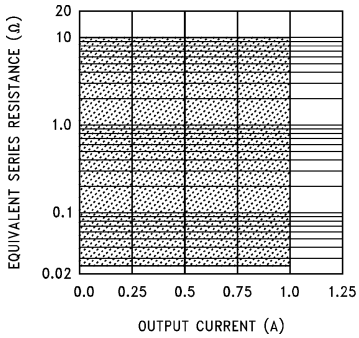

Figure 28. Output Capacitor ESR

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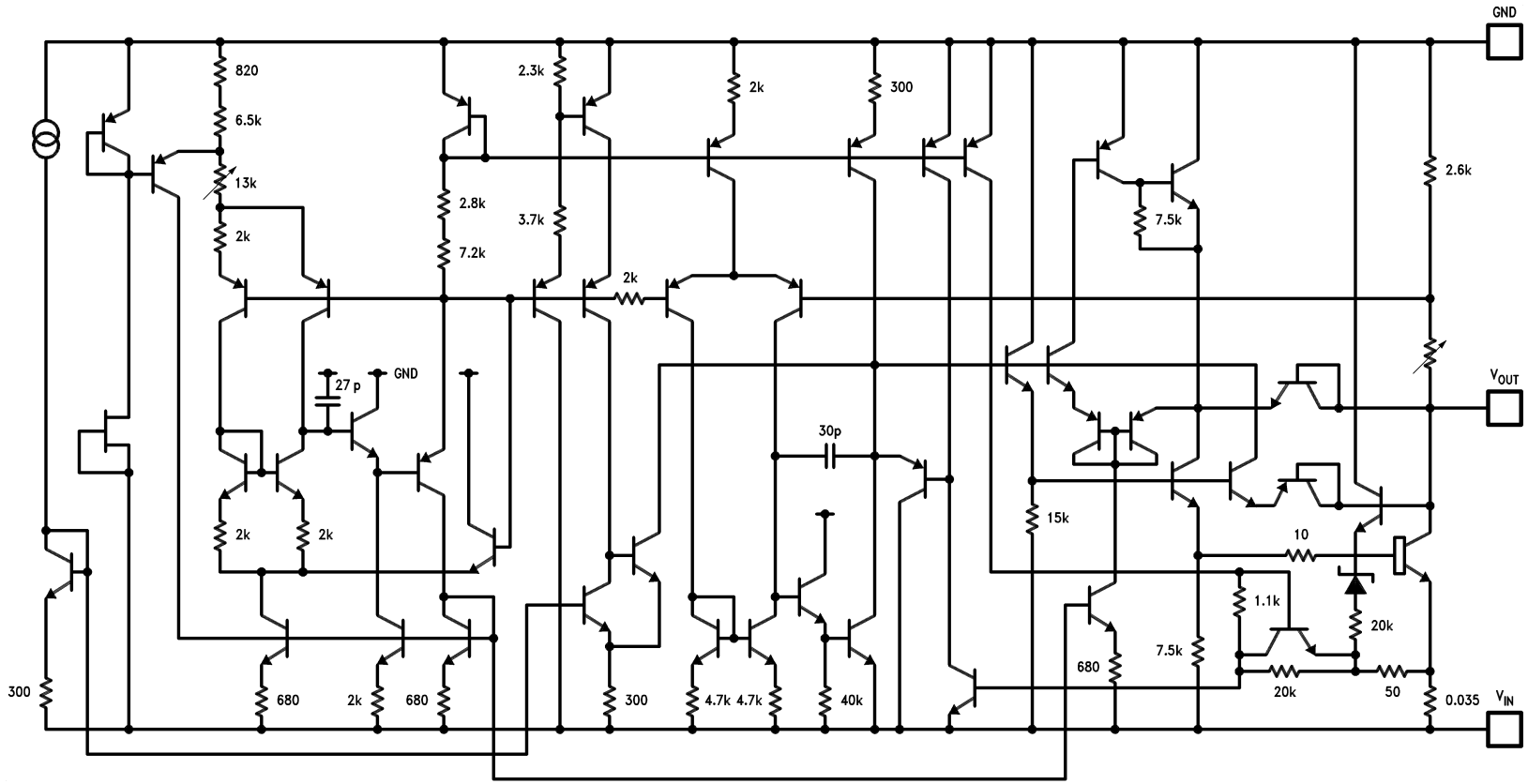
Equivalent Schematic



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REVISION HISTORY

Changes from Revision C (April 2013) to Revision D	Page
• Changed layout of National Data Sheet to TI format	11

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM2990S-12	NRND	DDPAK/ TO-263	KTT	3	45	TBD	Call TI	Call TI	-40 to 125	LM2990S -12 P+	
LM2990S-12/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2990S -12 P+	Samples
LM2990S-15	NRND	DDPAK/ TO-263	KTT	3	45	TBD	Call TI	Call TI	-40 to 125	LM2990S -15 P+	
LM2990S-15/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2990S -15 P+	Samples
LM2990S-5.0	NRND	DDPAK/ TO-263	KTT	3	45	TBD	Call TI	Call TI	-40 to 125	LM2990S -5.0 P+	
LM2990S-5.0/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2990S -5.0 P+	Samples
LM2990SX-12	NRND	DDPAK/ TO-263	KTT	3	500	TBD	Call TI	Call TI	-40 to 125	LM2990S -12 P+	
LM2990SX-12/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2990S -12 P+	Samples
LM2990SX-15	NRND	DDPAK/ TO-263	KTT	3	500	TBD	Call TI	Call TI	-40 to 125	LM2990S -15 P+	
LM2990SX-15/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2990S -15 P+	Samples
LM2990SX-5.0	NRND	DDPAK/ TO-263	KTT	3	500	TBD	Call TI	Call TI	-40 to 125	LM2990S -5.0 P+	
LM2990SX-5.0/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2990S -5.0 P+	Samples
LM2990T-12	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	-40 to 125	LM2990T -12 P+	
LM2990T-12/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2990T -12 P+	Samples
LM2990T-15	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	-40 to 125	LM2990T -15 P+	
LM2990T-15/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2990T -15 P+	Samples
LM2990T-5.0	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	-40 to 125	LM2990T -5.0 P+	

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM2990T-5.0/NOPB	ACTIVE	TO-220	NDE	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2990T -5.0 P+	Samples
LM2990T-5.2	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	-40 to 125	LM2990T -5.2 P+	
LM2990T-5.2/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2990T -5.2 P+	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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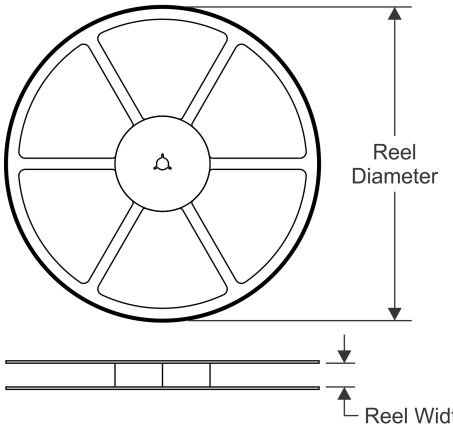
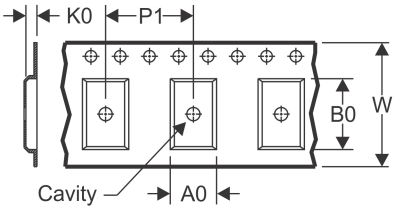
TAPE AND REEL INFORMATION

REEL DIMENSIONS

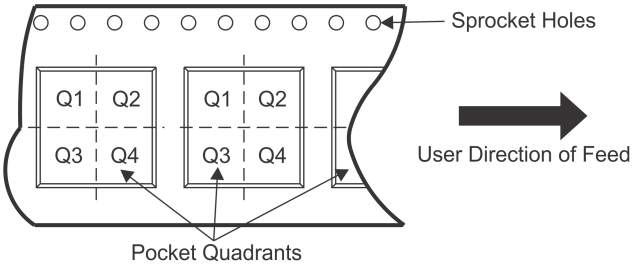


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2990SX-12	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM2990SX-12/NOPB	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM2990SX-15	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM2990SX-15/NOPB	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM2990SX-5.0	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM2990SX-5.0/NOPB	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2

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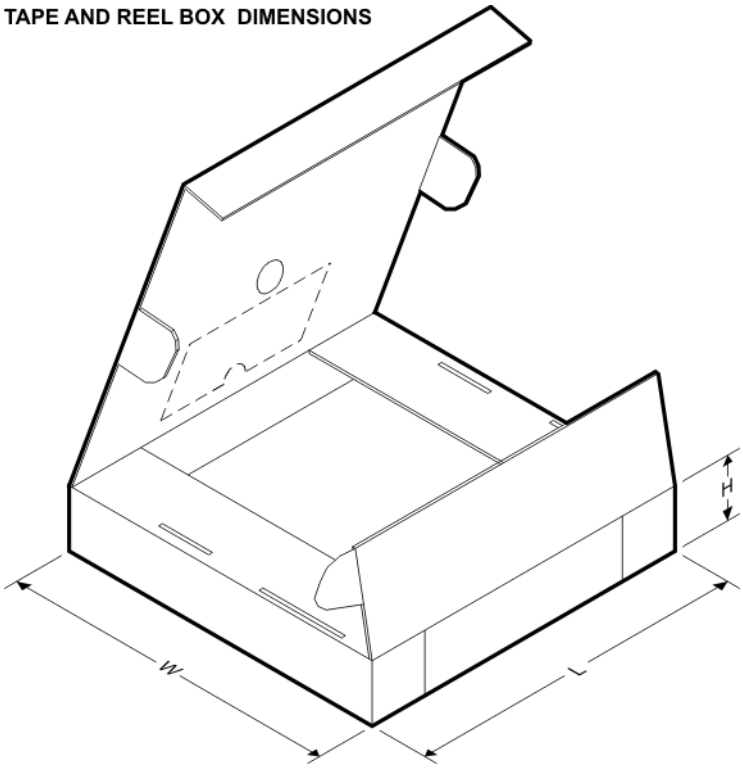
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2990SX-12	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0
LM2990SX-12/NOPB	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0
LM2990SX-15	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0
LM2990SX-15/NOPB	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0
LM2990SX-5.0	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0
LM2990SX-5.0/NOPB	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0

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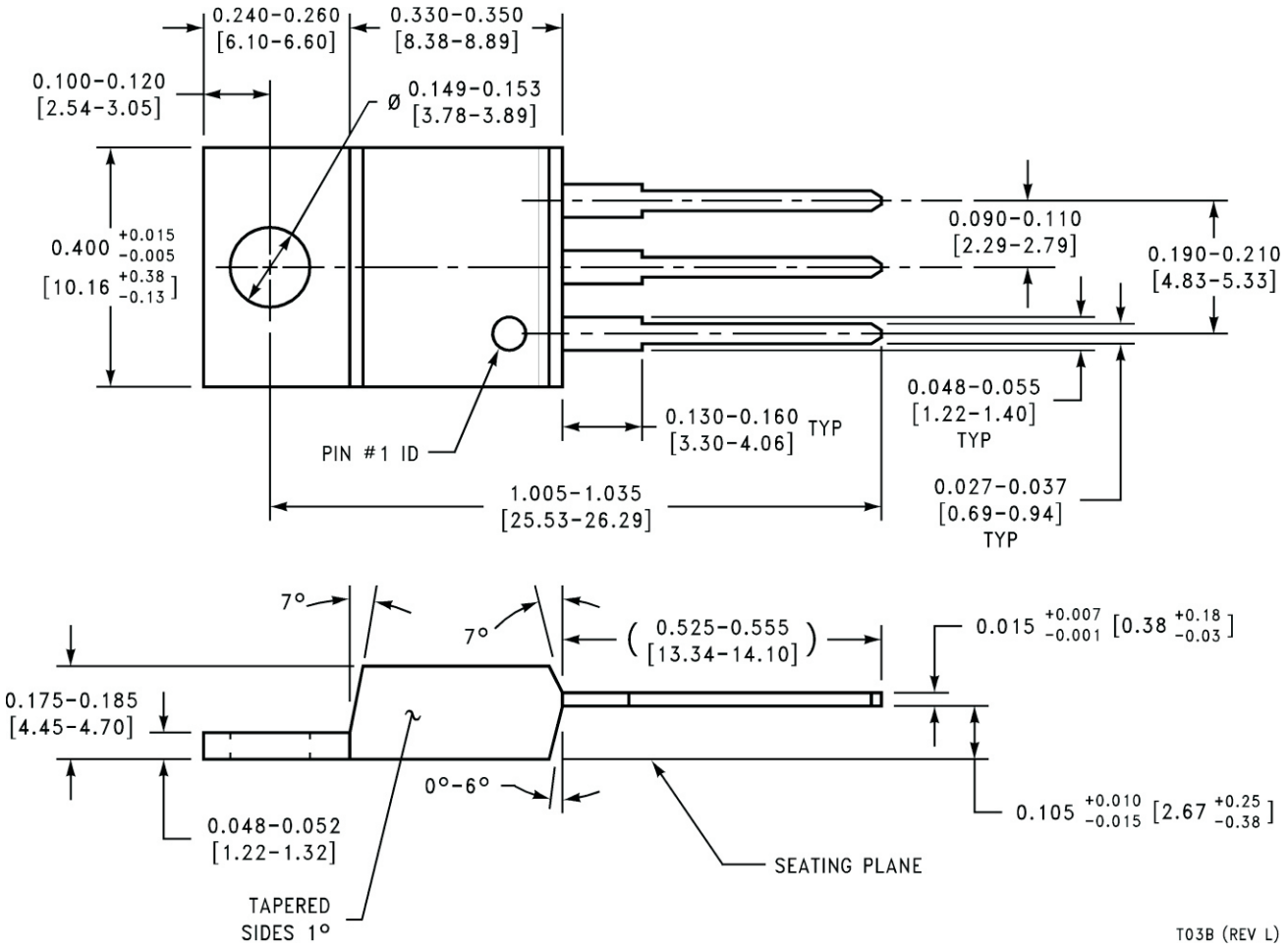
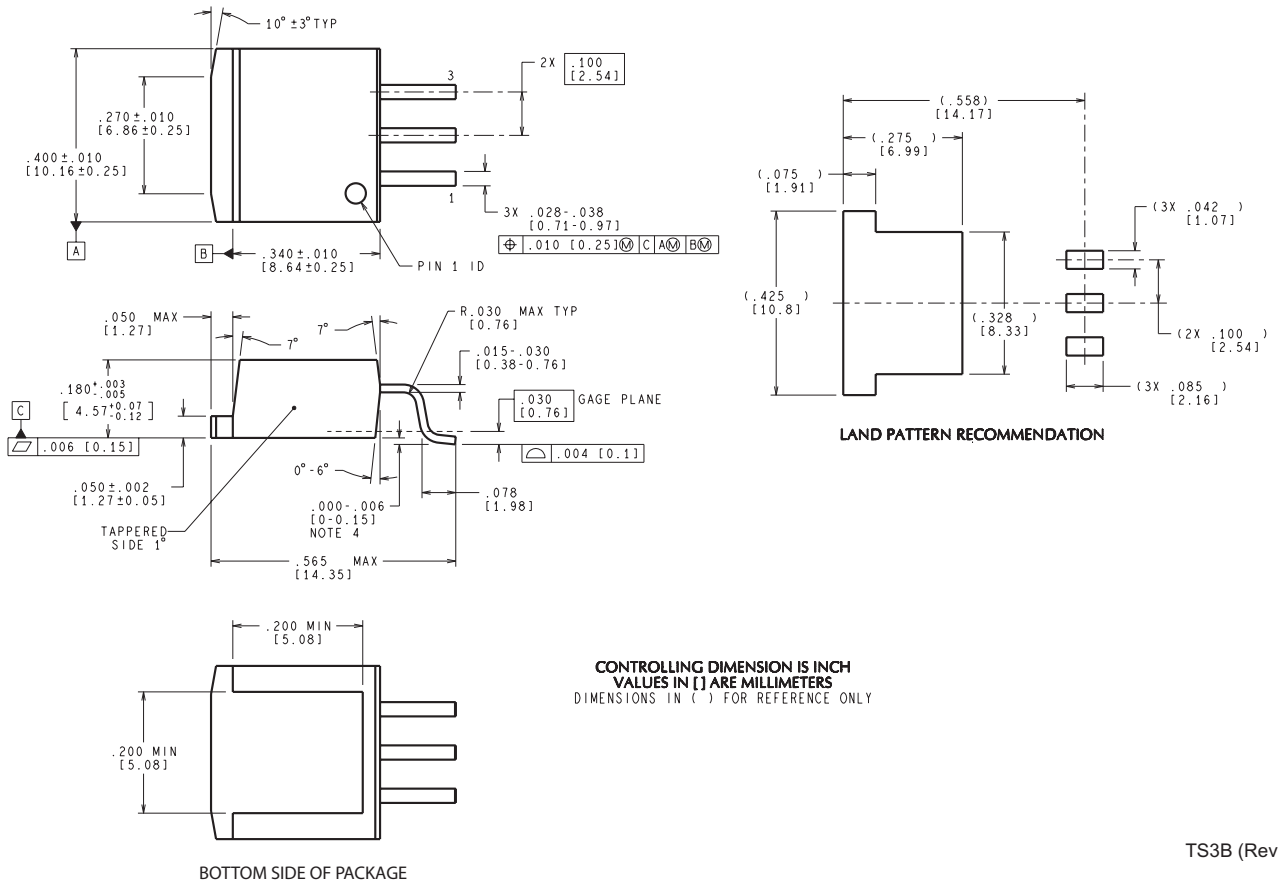
NDE0003B


0.240-0.260
[6.10-6.60]
0.330-0.350
[8.38-8.89]
0.100-0.120
[2.54-3.05]
Ø 0.149-0.153
[3.78-3.89]
0.400 +0.015 -0.005
[10.16 +0.38 -0.13]
0.090-0.110
[2.29-2.79]
0.190-0.210
[4.83-5.33]
0.048-0.055
[1.22-1.40]
TYP
0.130-0.160 TYP
[3.30-4.06]
PIN #1 ID
1.005-1.035
[25.53-26.29]
0.027-0.037
[0.69-0.94]
TYP
7°
7°
(0.525-0.555)
[13.34-14.10]
0.015 +0.007 -0.001 [0.38 +0.18 -0.03]
0.175-0.185
[4.45-4.70]
0°-6°
0.105 +0.010 -0.015 [2.67 +0.25 -0.38]
0.048-0.052
[1.22-1.32]
SEATING PLANE
TAPERED
SIDES 1°
T03B (REV L)

KTT0003B


10° ±3° TYP
2X .100 [2.54]
.270±.010 [6.86±0.25]
.400±.010 [10.16±0.25]
3X .028-.038 [0.71-0.97]
.010 [0.25] C A B
.340±.010 [8.64±0.25]
PIN 1 ID
.050 MAX [1.27]
7°
R.030 MAX TYP [0.76]
.015-.030 [0.38-0.76]
.030 [0.76] GAGE PLANE
.006 [0.15]
.004 [0.1]
0°-6°
.050±.002 [1.27±0.05]
.000-.006 [0-0.15] NOTE 4
.078 [1.98]
TAPPERED SIDE 1°
.565 MAX [14.35]
(.558) [14.17]
(.275) [6.99]
(.075) [1.91]
(3X .042) [1.07]
(.425) [10.8]
(.328) [8.33]
(2X .100) [2.54]
(3X .085) [2.16]
LAND PATTERN RECOMMENDATION
.200 MIN [5.08]
.200 MIN [5.08]
BOTTOM SIDE OF PACKAGE
CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY
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OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
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